

LOW/HIGH TEMPERATURE SUBSTRATE HOLDER TO REDUCE EDGE ROLLOFF AND BACKSIDE DAMAGE

Abstract of the Disclosure

A substrate holder for processing a semiconductor substrate that minimizes substrate non-uniformities as well as backside damage. The substrate holder includes one or more support elements, such as a plurality of veins configured in an annular ring to support an outer edge of a substrate. The veins are configured to support a substrate of a particular size in a support plane defined by the top surfaces of the veins. The substrate holder also has one or more annular grooves formed in the top surface of the holder. In a preferred embodiment, the substrate holder also has a raised annular ring positioned radially inward of the grooves and the support elements. The top surface of the raised annular ring is no higher than the top surfaces of the veins.

PATENT

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